

ABSTRACT OF THE DISCLOSURE

The present invention relates to a method for manufacturing a low roughness electrodeposited copper foil, and an electrodeposited copper foil manufactured thereby, and uses an electrolyte which basically consists of a sulfuric acid, a copper ion and a chloride ion is adapted with an additive which consists of a HEC (Hydroxyethyl Cellulose) of 0.05~50ppm, a SPS (bis(sodiumsulfopropyl)disulfide) of 0.05~20ppm, and a gelatin of 0.1~100ppm. The present invention is adapted to manufacture a low roughness electrodeposited copper foil using a conventional copper foil manufacture facility and the electrodeposited copper foil according to the present invention is adapted as a material for a copper clad laminate for a printed circuit substrate and an electrode material for a lithium ion battery.